

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Application of

July 17, 2003

Hideo KOBAYASHI, Shinichi SHINOHARA, Hironobu NISHIMURA, and Yukio  
UTSUNOMIYA

For : METHOD AND APPARATUS FOR CURING ADHESIVE  
BETWEEN SUBSTRATES, AND DISK SUBSTRATES BONDING  
APPARATUS

Our Docket : SHX 340

**Mail Stop: Patent Application**

Commissioner for Patents

P.O. Box 1450

Alexandria, Virginia 22313

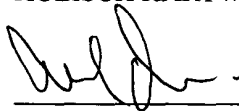
Sir:

**CLAIM OF FOREIGN PRIORITY**

Applicants hereby claim foreign priority benefits under 35 U.S.C. § 119(a)-(d) or § 365(b) of any foreign application(s) for patent or inventor's certificate, or § 365(a) of any PCT International application which designated at least one country other than the United States, listed below.

1. Japanese Patent Application Number: 2002-209897.  
Filed with the Japanese Patent Office on: July 18, 2002.
2. Japanese Patent Application Number: 2002-307283.  
Filed with the Japanese Patent Office on: October 22, 2002.
3. Japanese Patent Application Number: 2002-307385.  
Filed with the Japanese Patent Office on: October 22, 2002.
4. Japanese Patent Application Number: 2003-188734.  
Filed with the Japanese Patent Office on: June 30, 2003.

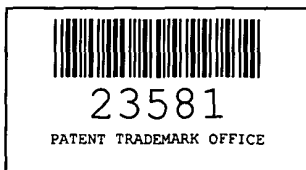
Respectfully submitted,  
KOLISCH HARTWELL, P.C.



Mark D. Alleman  
Registration No. 42,257  
Of Attorneys/Agents for Applicants  
Customer No. 23581  
520 S.W. Yamhill Street, Suite 200  
Portland, Oregon 97204  
Telephone: (503) 224-6655  
Facsimile: (503) 295-6679

July 17, 2003

Date of Mailing



MDA:gp  
Enclosures